

**STACKED SEMICONDUCTOR DEVICE HAVING MASK MOUNTED IN
BETWEEN STACKED DIES**

ABSTRACT OF THE DISCLOSURE

5 A stacked semiconductor device has a substrate having a conductor pattern thereon and the conductor pattern has a plurality of pads. A first die is mounted on the substrate and is electrically connected to the pads of the conductor pattern by gold wires. A first insulating layer is mounted on the substrate to cover the first die and the gold wires. A mask, which has a top and an annular sidewall, is mounted on the
10 substrate to cover the first insulating layer and the first die. A second die is mounted on the top of the mask and is electrically connected to the pads of the connector pattern by gold wires. A second insulating layer is mounted on the substrate to cover the second die and the gold wires.